Advanced Monolithic X-Band GaAs MMIC Receiver - Design and Reliability Issues in Medium Scale Integration

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OUTLINE

- o Objectives
- o Advanced deep space spacecraft transponder
- o Advanced MMIC GaAs X-band receiver chip
- o Performance of MMIC chips from the first iteration
- o Summary

Advanced Transponder Development Objectives

- o Develop and evaluate MMIC technology for advanced X-band and Ka-band transponders to reduce demand on spacecraft resources:
 - Mass
 - Volume
 - Power

- o Improve reliability
- Reduce flight hardware costs

ADVANCED DEEP SPACE SPACECRAFT TRANSPONDERS

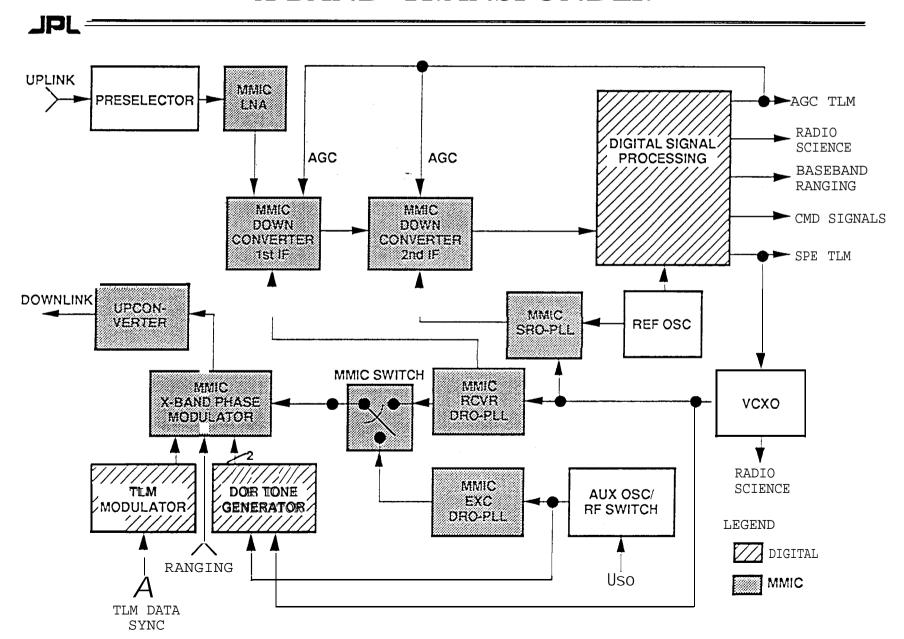
JPL:

Telecommunication Transponders for deep space spacecraft applications provide independent uplink command and turn around ranging functions, as well as do wnlink telemetry and radiometric capabilities

FUNCTIONS

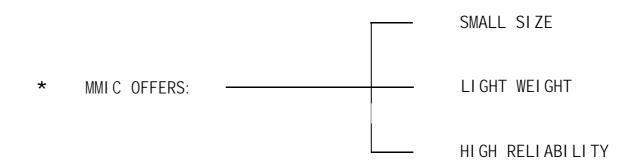
- o Precision phase/frequency reference transfer from the uplink signal
- θ Demodulation of the command and ranging signals from the uplink carrier
- θ Generation of a coherent or non-coherent downlink tracking signal for the earth based Deep Space Network .
- 0 Provide downlink signal modulation with composite telemetry data and turn around ranging or differential one-way ranging signals
- 0 Provide a functional capability to utilize an external ultra stable oscillator to generate the downlink signal
- 0 Provide reference signals for radio science experiments

ADVANCED DEEP SPACE SPACECRAFT X-BAND TRANSPONDER



ADVANTAGES OF MONOLITHIC MICROWAVE INTEGRATED CIRCUIT (MMIC)

- * ALL COMPONENTS INTEGRATED ON "CHIP"
- * NO / LOW INTERCONNECTS



ION IMPLANTED MONOLITHIC MICROWAVE INTEGRATED CIRCUIT PROCESS

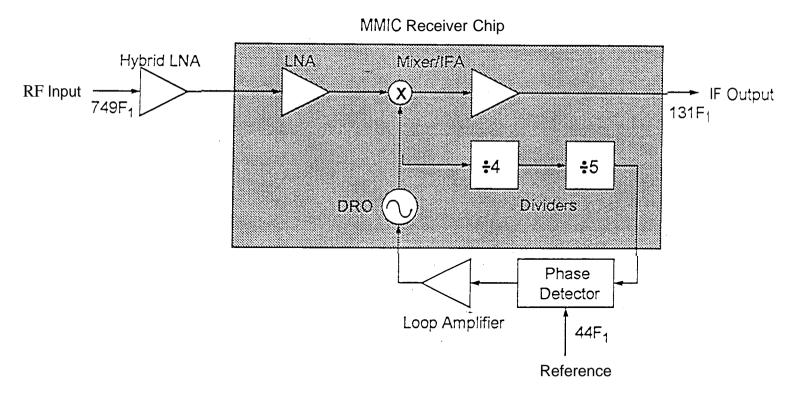
- * HIGH REPEATABILITY
- * EXCELLENT UNIFORMITY
- * LOW COST IN VOLUME PRODUCTION



HIGH RELIABILITY DESIGN

- o Judicious design, ion implanted GaAs materials in conjunction with refractory metal gate process to form the MESFET active devices are used
 - Increased "yield-to-performance"
 - Excellent stability at elevated temperatures
 - Improved overall reliability
- o Reduced DC and RF stress on active and passive circuits
 - Longer MTBF
- θ Die attached to thermal expansion matched material
 - Reduced thermal cycling stress
- 0 Hermetically sealed package
 - Controlled, moisture free environment
- 0 Compatibility with eventual higher level integration
 - Minimal number of interconnects

Advanced Monolithic GaAs X-Band Receiver Chip



Projected Chip Size ≤ 20 mm²



MMIC CHIP SIZE SUMMARY

LNA / GAIN BLOCK 2.0 X 1.25 MM

MI XER 2. 0 X 1.25 MM

IF AMPLIFIER 2.0 X 1.0 MM

VDSO 1. 4 XO. 9 MM

POWER SPLITTER 0.5 XO.63 MM

DIVIDE BY FOUR $2.0 \times 1.5 \text{ MM}$

DIVIDE BY FIVE 4.2 X 2.0 MM

1) <u>RF Amplifier</u> (Monolithic)

<u>PARAMETER</u>	<u>GOAL</u>	PREDI CTED
FREQUENCY	7.1 - 7.3 GHz	6.5 -7.8GHz
GAIN	20 dB	20 dB
NOISE FIGURE	3 dB	2.9 dB
INPUT VSWR	2:1	1.5:1
OUTPUT VSWR	2:1	1.5:1
IMAGE REJECTION		-30 dBc
P(1 dB)		7 dBm
POWER CONSUMPTION		100 mW
CHIP SIZE		1.9 x 1.25 mm

2) MIXER (Monolithic)

<u>PARAMETER</u>	<u>GOAL</u>	PREDI CTED
RF FREQUENCY	7. 1 ⁻ 7. 3 GHz	7.0 - 7.5 GHz
LO FREQUENCY	8.353 -8.553 GHz	8.1 -8.7 GHz
IF FREQUENCY	1. 253 GHz	1.253 GHz
LO POWER LEVEL		10 dBm
CONVERSION LOSS		10 dB
POWER CONSUMPTION		400 mW
CHIP SIZE		$1.9 \times 1.0 \text{ mm}$

3) <u>VOLTAGE CONTROLLED DIELECTRIC STABILIZED OSCILLATOR</u> (Monolithic)

<u>PARAMETER</u>	<u>GOAL</u>	PREDI CTED
FREQUENCY BAND	8.353 - 8.553 GHz	TBD
OUTPUT POWER	10 dBm	11 dBm
POWER CONSUMPTION		300 mW
CHIP SIZE		1.3 x 0.875 mm

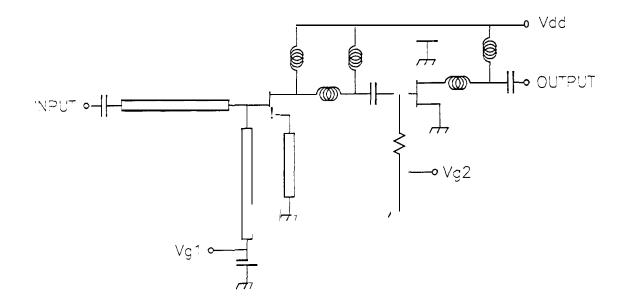
4) <u>IF AMPLIFIER</u> (Monolithic)

<u>PARAMETER</u>	<u>GOAL</u>	PREDI CTED
FREQUENCY	1. 253 GHz	1. 15 ⁻ 1. 35 GHz
GAI N	25 dB	25 dB
NOISE FIGURE	7.5 dB	7.3 dB
INPUT VSWR	2:1	1.5:1
OUTPUT VSWR	2:1	1.5:1
P(I dB)		7 dBm
POWER CONSUMPTION		. 100 mW
CHIP SI7F		1.9 x 1.0 mm

5) <u>DIVIDE BY FOUR</u> (Monolithic)		
<u>PARAMETER</u>	<u>GOAL</u>	PREDI CTED
INPUT FREQUENCY	8. 353 - 8. 553 GHz	8.15 - 8.8 GHz
INPUT POWER	O dBm	O dBm
OUTPUT POWER	0 dBm	5 dBm
HARMONIC OUTPUTS		-20 dBc
POWER CONSUMPTION		400 mW
CHIP SIZE		$2.0 \times 1.5 \text{ mm}$
6) <u>DIVIDE BY FIVE</u> (Monolithic)		
<u>PARAMETER</u>	<u>GOAL</u>	PREDI CTED
INPUT FREQUENCY	2.088 - 2.138 GHz	2.05 - 2.15 GHz
INPUT POWER		
TIVEOT TOWER	0 dBm	0 dBm
OUTPUT POWER	0 dBm 0 dBm	0 dBm 5 dBm
OUTPUT POWER		5 dBm

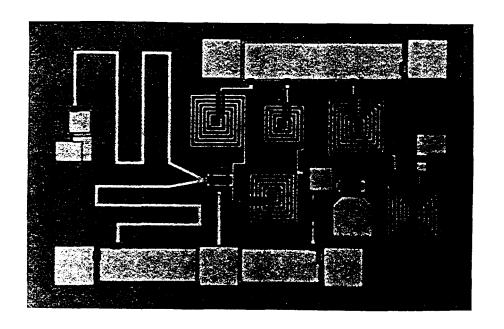


SCHEMATIC DIAGRAM OF THE GAAS MMIC INA / GAIN BLOCK



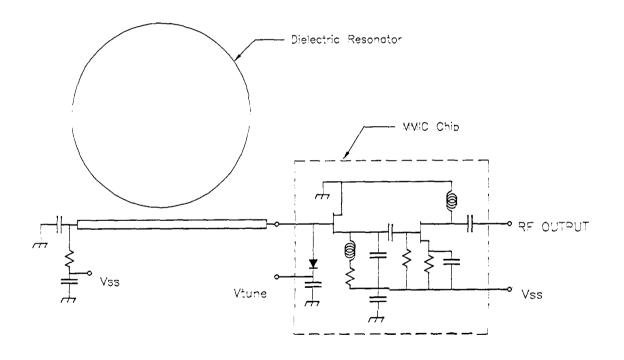


PHOTOMICROGRAPH OF THE GaAS MMIC LNA / GAIN BLOCK CHIP

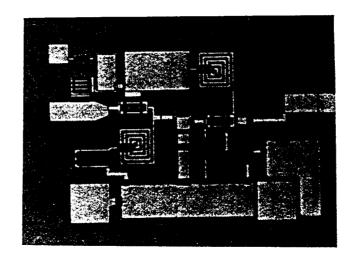




SCHEMATIC DIAGRAM OF THE GaAs MMIC VOLTAGE CONTROLLED DSO

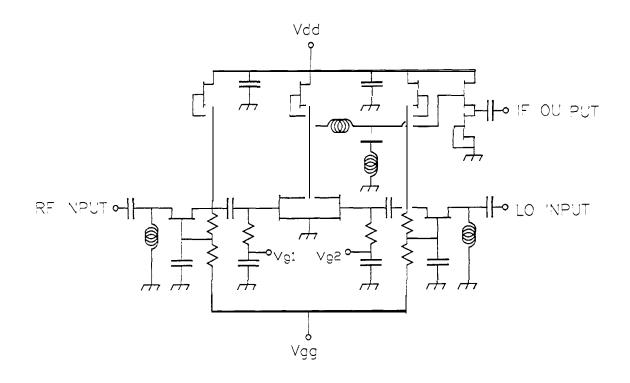


PHOTOMI CROGRAPH OF THE GAAS MMIC VOLTAGE CONTROLLED DSO CHIP

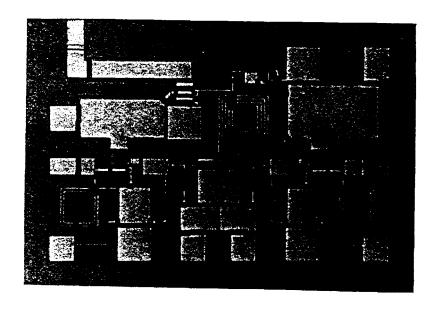




SCHEMATIC DIAGRAM OF THE GaAs MMIC MIXER

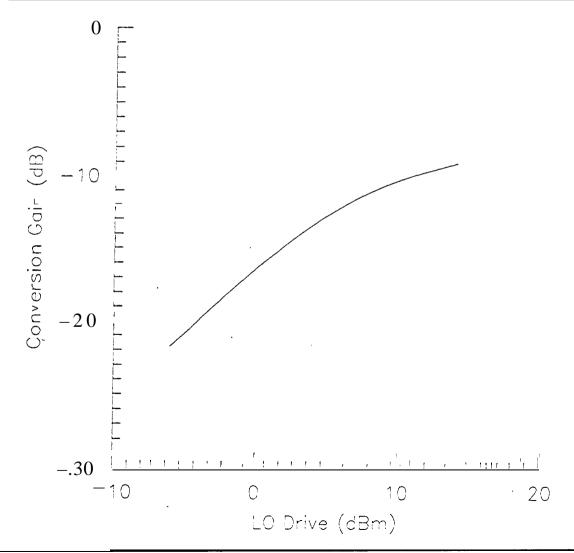


PHOTOMI CROGRAPH OF THE GaAs MMIC MIXER



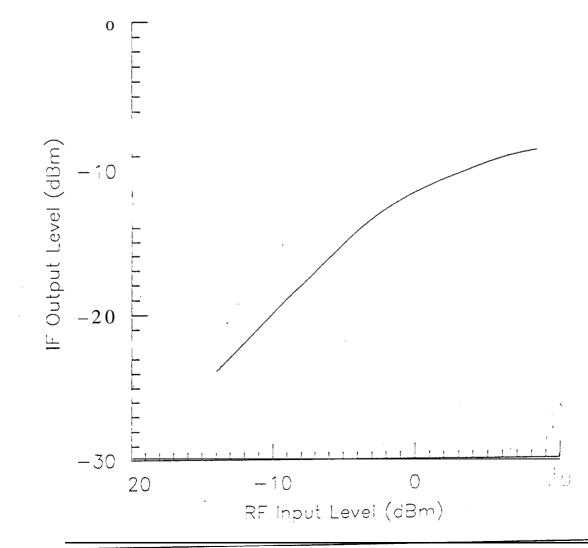


CONVERSION LOSS VS LO DRIVE OF A FIRST-ITERATION MONOLITHIC MIXER

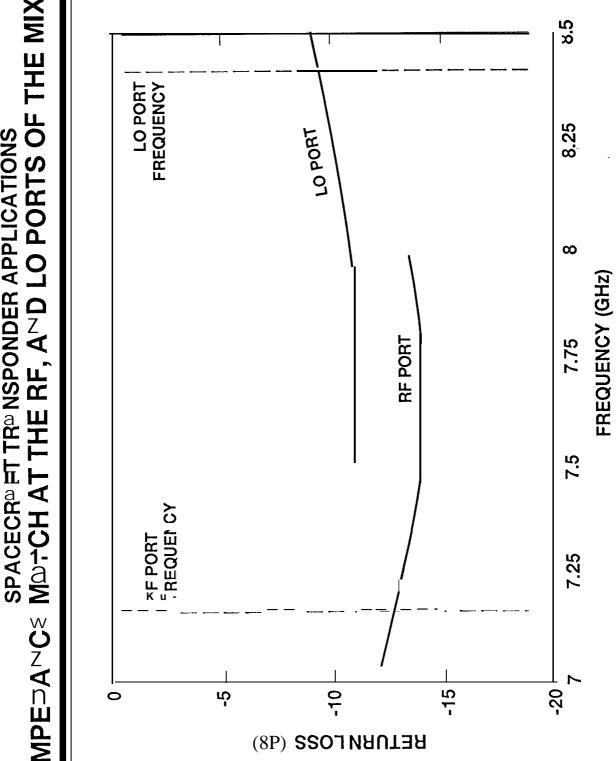




1F OUTPUT LEVEL VS RF INPUT POWER OF A FIRST-ITERATION MONOLITHIC MIXER

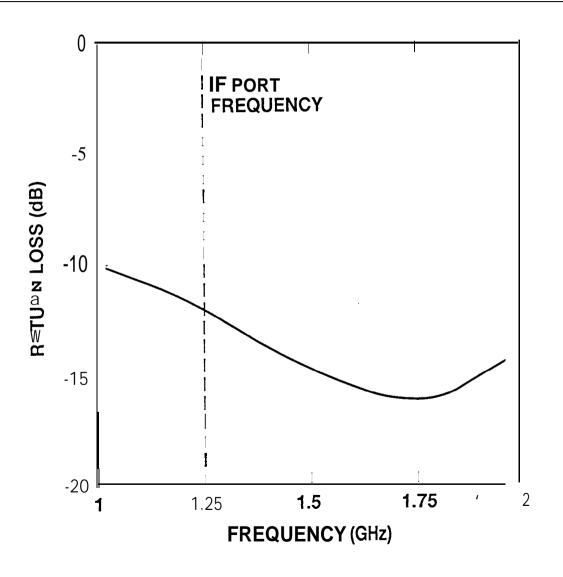


IMPEDANC≤ MOHCH AT THE RF, AND LO PORTS OF THE MIX≤R SPACECR® FT TR® NSPONDER APPLICATIONS MONOLITHIC GAAS FRONT END FOR

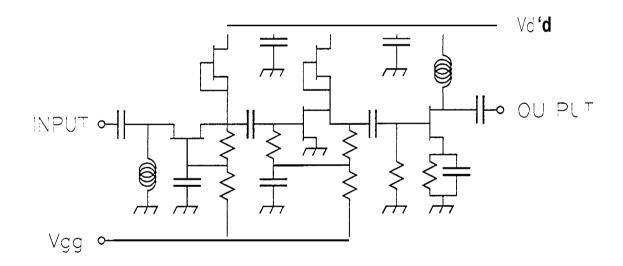




IMPEDANCE MATCH AT THE IF PORT OF THE MIXER

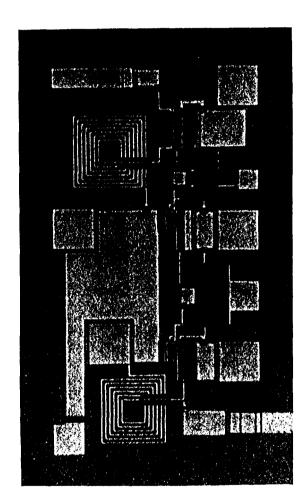


SCHEMATIC DIAGRAM OF THE GaAS MMIC IF AMPLIFIER



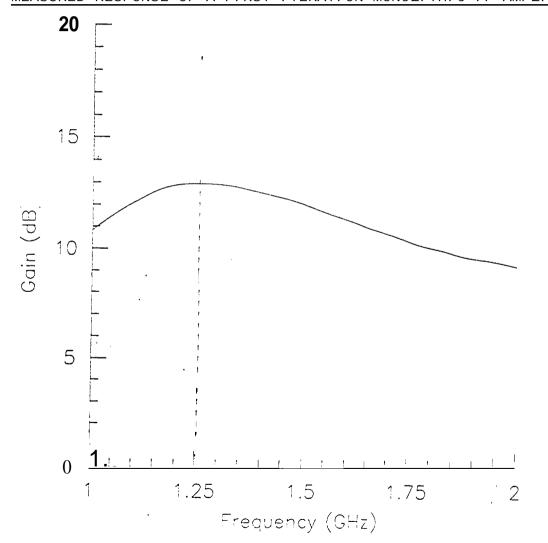


PHOTOMICROGRAPH OF THE GAAS MMIC IF AMPLIFIER

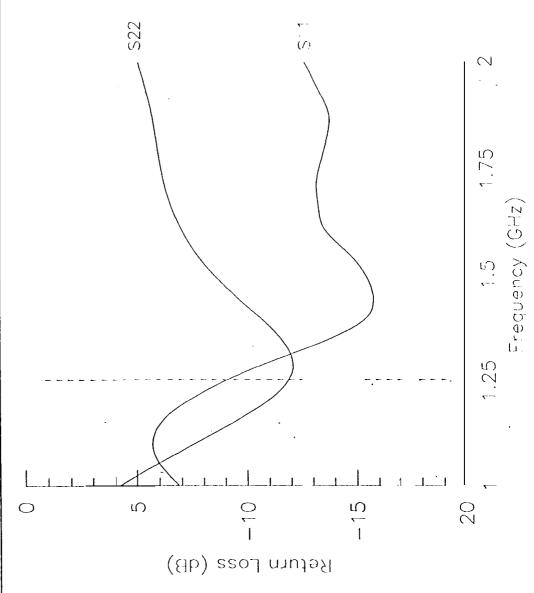




MEASURED RESPONSE OF A FIRST-ITERATION MONOLITHIC IF AMPLIFIER



MEASURED INPUT & OUTPUT MATCH OF A FIRST-ITERATION MONOLITHIC IF AMPLIFIER





Approaches Capable of Coherent Microwave Frequency Division

o REGENERATIVE DIVIDER

- Moderate N, Operation to 60 GHz
- Large chip size
- 0 to + 10 dBm input, Low conversion loss with amplifier
- Low phase noise

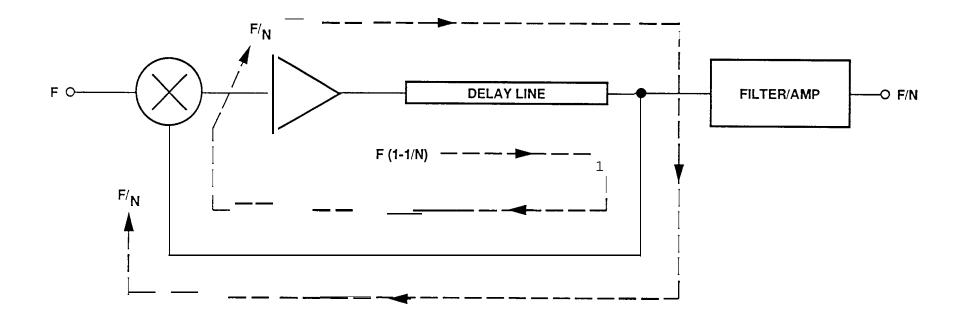
o BLOCKING OSCILLATOR

- High N, Operation to 8 GHz
- Medium chip size
- 0 to + 10 dBm input, Conversion gain possible
- Moderate phase noise

o PARAMETRIC DIVIDER

- Low N, Operation to 60 GHz
- Small but not easily integrated
- 0 to + 15 dBm input, High conversion loss
- Moderate phase noise

MONOLITHIC GaAs FRONT END FOR SPACECRAFT TRANSPONDER APPLICATIONS REGENERATIVE DIVIDE-BY-N FREQUENCY DIVIDER

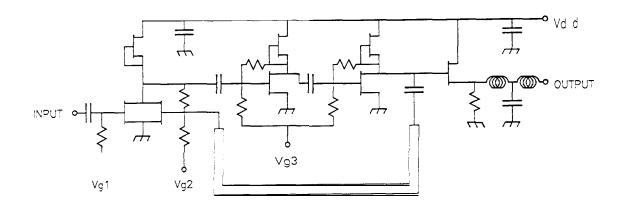


Regenerative Dividers

A Mixing divider is a nonlinear circuit which regeneratively supports the subharmonic oscillation in response to a driving input signal

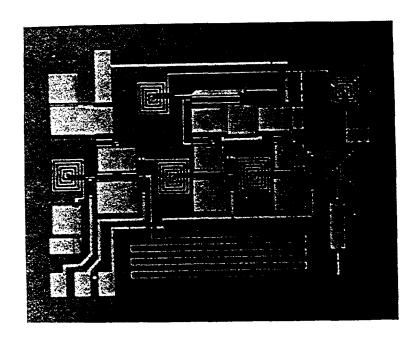
- o Input signal mixes with noise to regeneratively produce Subharmonic frequency, $F_{ou}t = F/N$; and idler frequency, $F_1 = F(1 - 1/N)$
- 0 Requires gain and correct phase shift at both the desired output frequency and the idler frequency
 - Difficult at higher frequencies, and large N
- 0 Requires CW input signal
- 0 N should be preferably an even number Shorter delay line structure Less spurious output signal
- 0 Has been experimentally demonstrated at 12 GHz (N = 4, and 2), and at 16 GHz (N = 2),

SCHEMATIC DIAGRAM OF THE GAAS MMIC REGENERATIVE DIVIDE-BY-FOUR CIRCUIT



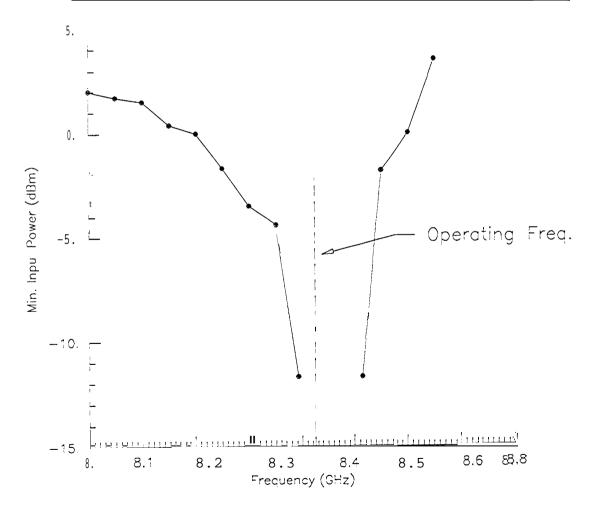


PHOTOMICROGRAPH OF THE GAAS MMIC REGENERATIVE DIVIDE-BY-FOUR CIRCUIT

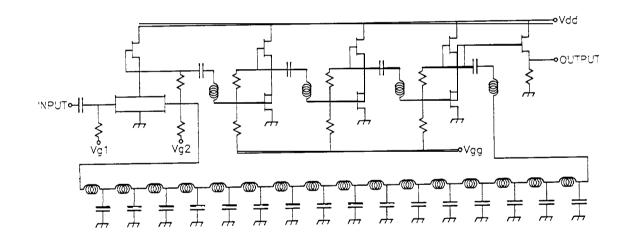




MEASURED INPUT SENSITIVITY OF THE DIVIDE BY FOUR MMIC.

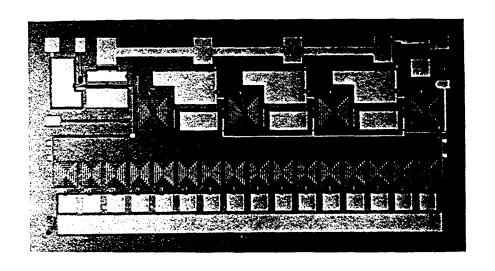


SCHEMATIC DIAGRAM OF THE GAAS MMIC REGENERATIVE DIVIDE-BY-FIVE CIRCUIT



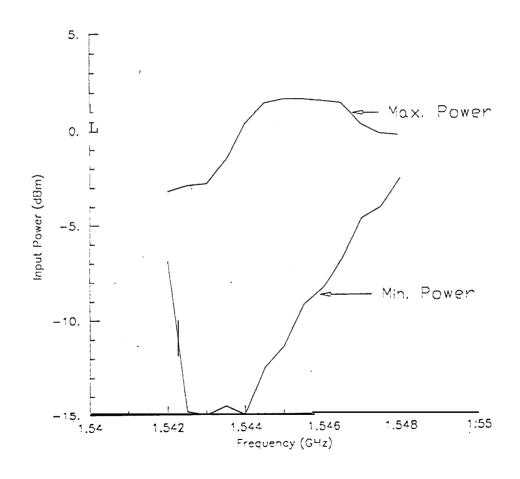


PHOTOMICROGRAPH OF THE GAAS MMIC REGENERATIVE DIVIDE-BY-FIVE CIRCUIT





MEASURED INPUT SENSITIVITY OF THE DIVIDE BY FIVE MMIC





SUMMARY

- o Seven different MMIC circuits on the same GaAs substrate have been designed and fabricated for the transponder receiver front end applications
- o Judicious design, ion implanted process, and refractory metal MESFETS are used to increase the yield, and reliability of the receiver front end
- o First iteration circuits function close to expectations
 - VCO, mixer, and divide-by-four circuits meet the design requirements
 - RF amplifier, IF amplifier, and divide-by-five circuit with an alternative phase compensation circuit will be redesigned to meet the design requirements
- o A second design/fabrication iteration is planed to complete the MMIC receiver front end breadboard
- o Applicable to high reliability, small size, and light weight communication systems for micro spacecraft applications